

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wachovia Bank, National Association, as Agent	04/23/2007

RECEIVING PARTY DATA

Name:	Wachovia Capital Finance Corporation (New England), as Agent
Street Address:	One Post Office Square
City:	Boston
State/Country:	MASSACHUSETTS
Postal Code:	02109

PROPERTY NUMBERS Total: 40

Property Type	Number
Patent Number:	6905589
Patent Number:	6872894
Patent Number:	6900392
Application Number:	10811915
Application Number:	10915483
Application Number:	10394107
Application Number:	10394135
Application Number:	10811817
Application Number:	10616932
Application Number:	10409066
Application Number:	10679302
Application Number:	10643909
Application Number:	10630722
Application Number:	10449019
Application Number:	10868066

OP \$1600.00 6905589

PATENT

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REEL: 019304 FRAME: 0676

Application Number:	10423972
Application Number:	10812890
Application Number:	10812889
Application Number:	10661616
Application Number:	10900385
Application Number:	10900386
Application Number:	10757586
Application Number:	10740500
Application Number:	10920235
Application Number:	10740398
Application Number:	10737974
Application Number:	10790747
Application Number:	10882170
Application Number:	10882167
Application Number:	10991532
Application Number:	10953923
Application Number:	10860067
Application Number:	10860071
Application Number:	10968929
Application Number:	10955741
Application Number:	10991451
Application Number:	11031074
Application Number:	10322527
Patent Number:	6828514
Patent Number:	6815837

CORRESPONDENCE DATA

Fax Number: (917)368-7111

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Email: hlinehan@OSHR.com

Correspondent Name: Helen M. Linehan

Address Line 1: 230 Park Avenue

Address Line 4: New York, NEW YORK 10169

NAME OF SUBMITTER:	Helen M. Linehan
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Total Attachments: 8

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PATENT
REEL: 019304 FRAME: 0677

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NOTICE OF ASSIGNMENT AND ACCEPTANCE

Wachovia Bank, National Association,
as Agent
One Post Office Square, Suite 3600
Boston, Massachusetts 021109
Attn.: Portfolio Manager

April 23, 2007

Re: Endicott Interconnect Technologies, Inc.

Ladies and Gentlemen:

Wachovia Bank, National Association, in its capacity as agent pursuant to the Loan Agreement (as hereinafter defined) acting for and on behalf of the financial institutions which are parties thereto as lenders (in such capacity, "Agent"), and the financial institutions which are parties to the Loan Agreement as lenders (individually, each a "Lender" and collectively, "Lenders") have entered or are about to enter into financing arrangements pursuant to which Agent and Lenders may make loans and advances and provide other financial accommodations to Endicott Interconnect Technologies, Inc. ("Borrower") as set forth in the Loan and Security Agreement, dated April 7, 2005, by and among Borrower, Agent and Lenders (as the same now exists or may hereafter be amended, modified, supplemented, extended, renewed, restated or replaced, the "Loan Agreement"), and the other agreements, documents and instruments referred to therein or at any time executed and/or delivered in connection therewith or related thereto (all of the foregoing, together with the Loan Agreement, as the same now exist or may hereafter be amended, modified, supplemented, extended, renewed, restated or replaced, being collectively referred to herein as the "Financing Agreements"). Capitalized terms not otherwise defined herein shall have the respective meanings ascribed thereto in the Loan Agreement.

1. We hereby give you notice of, and request your consent to, the assignment by Wachovia Bank, National Association (the "Assignor") to Wachovia Capital Finance Corporation (New England) (the "Assignee") such that after giving effect to the assignment Assignee shall have an interest equal to one hundred (100%) percent of the total Commitments pursuant to the Assignment and Acceptance Agreement attached hereto (the "Assignment and Acceptance"). We understand that the Assignor's Commitment shall be reduced by \$37,000,000.

2. Assignee agrees that, upon receiving the consent of Agent to such assignment, Assignee will be bound by the terms of the Loan Agreement as fully and to the same extent as if the Assignee were the Lender originally holding such interest under the Loan Agreement.

3. The following administrative details apply to Assignee:

806808.1

(A) Notice address:

Assignee name: Wachovia Capital Finance Corporation (New England)

Address: One Post Office Square, Suite 3600, Boston, MA 02109

Attention: Portfolio Manager

Telephone: (617) 338-1998

Telecopier: (617) 338-1497

(B) Payment instructions:

Account No.: 5000000030305

ABA No.: 053000219

At: Wachovia Bank, National Association

Reference: Endicott Interconnect Technologies, Inc.

Attention: Wachovia Capital Finance Corporation (New England)

4. You are entitled to rely upon the representations, warranties and covenants of each of Assignor and Assignee contained in the Assignment and Acceptance.

IN WITNESS WHEREOF, Assignor and Assignee have caused this Notice of Assignment and Acceptance to be executed by their respective duly authorized officials, officers or agents as of the date first above mentioned.

Very truly yours,

WACHOVIA BANK, NATIONAL
ASSOCIATION

By: [Signature]

Title: MD

WACHOVIA CAPITAL FINANCE
CORPORATION (NEW ENGLAND)

By: [Signature]

Title: MD

ACKNOWLEDGED AND ASSIGNMENT
CONSENTED TO:

WACHOVIA BANK, NATIONAL ASSOCIATION,
as Agent

By: [Signature]

Title: MD



UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

SEPTEMBER 22, 2005

PTAS



102999012A

HELEN M. LINEHAN
OTTERBOURG, STEINDLER
ET AL
230 PARK AVENUE
NEW YORK, NY 10169

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 571-272-3350. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, MAIL STOP: ASSIGNMENT SERVICES DIVISION, P.O. BOX 1450, ALEXANDRIA, VA 22313.

RECORDATION DATE: 05/10/2005

REEL/FRAME: 016561/0605
NUMBER OF PAGES: 27

BRIEF: SECURITY AGREEMENT

ASSIGNOR:

ENDICOTT INTERCONNECT
TECHNOLOGIES, INC.

DOC DATE: 04/07/2005

ASSIGNEE:

WACHOVIA BANK, NATIONAL
ASSOCIATION, AS AGENT
ONE POST OFFICE SQUARE
BOSTON, MASSACHUSETTS 02109

SERIAL NUMBER: 10370529

FILING DATE: 02/24/2003

PATENT NUMBER: 6905589

ISSUE DATE: 06/14/2005

TITLE: CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME

SERIAL NUMBER: 10379575

FILING DATE: 03/06/2003

PATENT NUMBER: 6872894

ISSUE DATE: 03/29/2005

TITLE: INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE

SERIAL NUMBER: 10933260	FILING DATE: 09/03/2004
PATENT NUMBER: 6900392	ISSUE DATE: 05/31/2005
TITLE: INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE	
SERIAL NUMBER: 10811915	FILING DATE: 03/30/2004
PATENT NUMBER:	ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	
SERIAL NUMBER: 10915483	FILING DATE: 08/11/2004
PATENT NUMBER:	ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	
SERIAL NUMBER: 10394107	FILING DATE: 03/24/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: MULTI-CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	
SERIAL NUMBER: 10394135	FILING DATE: 03/24/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: INFORMATION HANDLING SYSTEM	
SERIAL NUMBER: 10811817	FILING DATE: 03/30/2004
PATENT NUMBER:	ISSUE DATE:
TITLE: HIGH SPEED CIRCUIT BOARD AND METHOD FOR FABRICATION	
SERIAL NUMBER: 10616932	FILING DATE: 07/11/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: METHOD OF TESTING PRINTED CIRCUIT BOARD OPENING SPACINGS	
SERIAL NUMBER: 10409066	FILING DATE: 04/09/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: MATERIAL SEPARATION TO FORM SEGMENTED PRODUCT	
SERIAL NUMBER: 10679302	FILING DATE: 10/07/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAME AND INFORMATION HANDLING SYSTEM USING SAME	
SERIAL NUMBER: 10643909	FILING DATE: 08/20/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	
SERIAL NUMBER: 10630722	FILING DATE: 07/31/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: ELECTRONIC COMPONENT TEST APPARATUS	
SERIAL NUMBER: 10449019	FILING DATE: 06/02/2003
PATENT NUMBER:	ISSUE DATE:
TITLE: ELECTRONIC CARD	
SERIAL NUMBER: 10868066	FILING DATE: 06/16/2004
PATENT NUMBER:	ISSUE DATE:
TITLE: ELECTRONIC PCKAGE WITH CONDUCTIVE PAD CAPABLE OF WITHSTANDING SIGNIFICANT LOADS AND INFORMATION HANDLING SYSTEM UTILIZING SAME	

SERIAL NUMBER: 10423972 FILING DATE: 04/28/2003
PATENT NUMBER: ISSUE DATE:
TITLE: PINNED ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD

SERIAL NUMBER: 10812890 FILING DATE: 03/31/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY
UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME

SERIAL NUMBER: 10812889 FILING DATE: 03/31/2004
PATENT NUMBER: ISSUE DATE:
TITLE: DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN
CIRCUITIZED SUBSTRATES

SERIAL NUMBER: 10661616 FILING DATE: 09/15/2003
PATENT NUMBER: ISSUE DATE:
TITLE: STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD
OF MAKING SAME

SERIAL NUMBER: 10900385 FILING DATE: 07/28/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE, METHOD
OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION
HANDLING SYSTEM UTILIZING SAME

SERIAL NUMBER: 10900386 FILING DATE: 07/28/2004
PATENT NUMBER: ISSUE DATE:
TITLE: ELECTRICAL ASSEMBLY WITH INTERNAL MEMORY CIRCUITIZED SUBSTRATE
HAVING ELECTRONIC COMPONENTS POSITIONED THEREON, METHOD OF MAKING
SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME

SERIAL NUMBER: 10757586 FILING DATE: 01/15/2004
PATENT NUMBER: ISSUE DATE:
TITLE: METHOD OF MAKING PRINTED CIRCUIT BOARD WITH ELECTROPLATED
CONDUCTIVE THROUGH HOLES AND BOARD RESULTING THEREFROM

SERIAL NUMBER: 10740500 FILING DATE: 12/22/2003
PATENT NUMBER: ISSUE DATE:
TITLE: ITEM IDENTIFICATION AND CONTROL SYSTEM

SERIAL NUMBER: 10920235 FILING DATE: 08/18/2004
PATENT NUMBER: ISSUE DATE:
TITLE: LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE, METHOD OF MAKING
SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING
SYSTEM UTILIZING SAME

SERIAL NUMBER: 10740398 FILING DATE: 12/22/2003
PATENT NUMBER: ISSUE DATE:
TITLE: PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE

SERIAL NUMBER: 10737974 FILING DATE: 12/18/2003
PATENT NUMBER: ISSUE DATE:
TITLE: METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND
BOARD RESULTING THEREFROM

SERIAL NUMBER: 10790747 FILING DATE: 03/03/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE WITH SIGNAL WIRE SHIELDING, ELECTRICAL
ASSEMBLY UTILIZING SAME AND METHOD OF MAKING

SERIAL NUMBER: 10882170 FILING DATE: 07/02/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE WITH FILLED ISOLATION BORDER, METHOD OF
MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION
HANDLING SYSTEM UTILIZING SAME

SERIAL NUMBER: 10882167 FILING DATE: 07/02/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING
SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING
SYSTEM UTILIZING SAME

SERIAL NUMBER: 10991532 FILING DATE: 11/19/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS
PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND
INFORMATION HANDLING SYSTEMS UTILIZING SAME

SERIAL NUMBER: 10953923 FILING DATE: 09/29/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATE WITH IMPROVED IMPEDANCE CONTROL CIRCUITRY,
METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING
SYSTEM UTILIZING SAME

SERIAL NUMBER: 10860067 FILING DATE: 06/04/2004
PATENT NUMBER: ISSUE DATE:
TITLE: METHOD AND SYSTEM FOR TRACKING GOODS

SERIAL NUMBER: 10860071 FILING DATE: 06/04/2004
PATENT NUMBER: ISSUE DATE:
TITLE: RADIO FREQUENCY DEVICE FOR TRACKING GOODS

SERIAL NUMBER: 10968929 FILING DATE: 10/21/2004
PATENT NUMBER: ISSUE DATE:
TITLE: METHOD OF MAKING A CIRCUITIZED SUBSTRATE HAVING A PLURALITY OF
SOLDER CONNECTION SITES THEREON

SERIAL NUMBER: 10955741 FILING DATE: 09/30/2004
PATENT NUMBER: ISSUE DATE:
TITLE: HIGH SPEED CIRCUITIZED SUBSTRATE WITH REDUCED THRU-HOLE STUB,
METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING
SAME

SERIAL NUMBER: 10991451 FILING DATE: 11/19/2004
PATENT NUMBER: ISSUE DATE:
TITLE: CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE
LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL
ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME

SERIAL NUMBER: 11031074 FILING DATE: 01/10/2005
PATENT NUMBER: ISSUE DATE:
TITLE: CAPACITOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED
SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING
SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM
UTILIZING SAID CIRCUITIZED SUBSTRATE

SERIAL NUMBER: 10322527 FILING DATE: 12/19/2002
PATENT NUMBER: 6809269 ISSUE DATE: 10/26/2004
TITLE: CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME

SERIAL NUMBER: 10354000 FILING DATE: 01/30/2003
PATENT NUMBER: 6828514 ISSUE DATE: 12/07/2004
TITLE: HIGH SPEED CIRCUIT BOARD AND METHOD FOR FABRICATION

SERIAL NUMBER: 10423877 FILING DATE: 04/28/2003
PATENT NUMBER: 6815837 ISSUE DATE: 11/09/2004
TITLE: ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD

STEVEN POST, EXAMINER
ASSIGNMENT DIVISION
OFFICE OF PUBLIC RECORDS